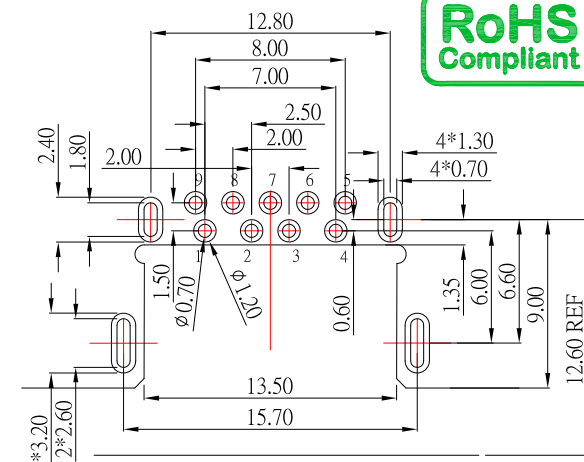
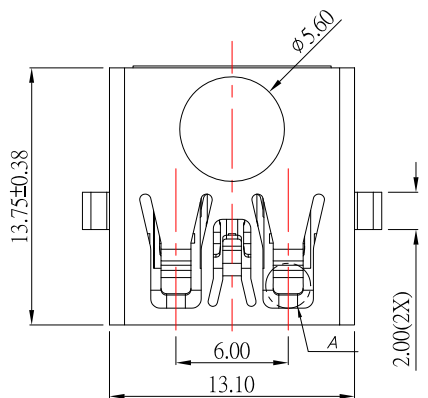




# SUA-110E18-30x-S242

鍍層厚度：

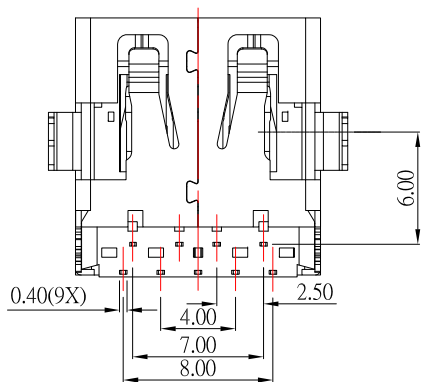
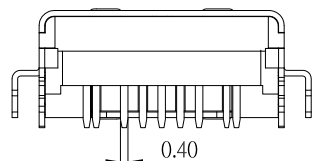
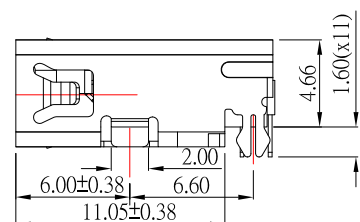
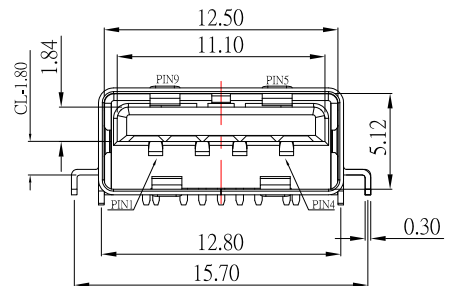
Blank	: 1u"
2	: 15u"
3	: 30u"



## RECOMMENDED PCB LAYOUT

NOTE:

- 1.MATERIAL:
  - 1.1 Housing: LCP
  - 1.2 Contact: Phosphor Bronze
  - 1.3 Shell: SUS201
- 2.Finish:
  - 2.1 Contact: Plated Gold in Mating Area ;  
Tin Plated on Solder Balls ;  
Nickel under plated overall
  - 2.2 Shell: Nickel under Plated surface layer
- 3.SPECIFICATION:
  - 3.1 Rate: 30V DC , 1.5 A
  - 3.2 Insulator Resistance:100MΩ Min
  - 3.3 Dielectric Strength: 500V AC
  - 3.4 Contact Resistance: 30mΩ Max
  - 3.5 Operation Temperature: -55°C ~ +85°C



**CONTACT** 建倚科技股份有限公司  
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :  
 Up to 5 ±0.2  
 Above 5 ~ 15 ±0.3  
 Above 15 ~ 30 ±0.4  
 Above 30 ~ 50 ±0.5  
 Angle ±0.3

3RD. ANGEL'S



UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	03/29/22			
CHECKED BY:	DATE	FINISH	MODLE	USB AF 3.0 SMT 沉板板上H4.46mm L13.75 無捲邊
Jacky Chen	03/29/22			
APPROVED BY:	DATE	SCALE	DWG NO.	SUA-110E18-30x-S242
Tony Kao	03/29/22	1 : 1	PART NO.	SUA-110E18-30x-S242
		SHEET NO.	1 of 1	SIZE A4 VER R2

ITEM NO.	DESCRIPTION	DRAWN	DATE
2	新增尺寸和更新樣式	Jack	032922
1	更新樣式	Jack	032522